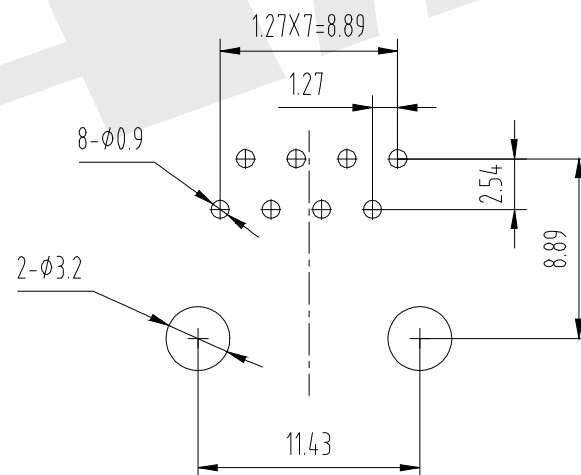
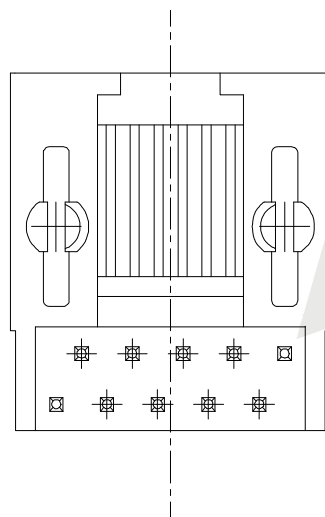
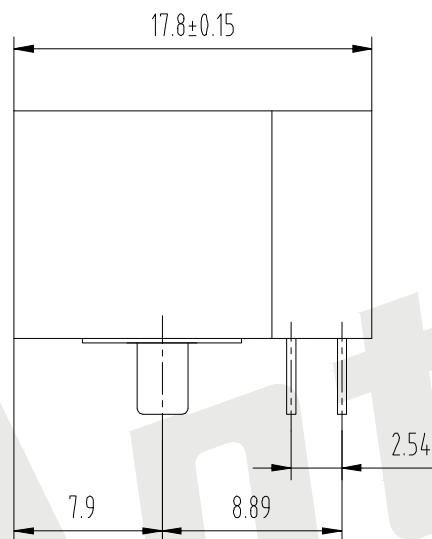
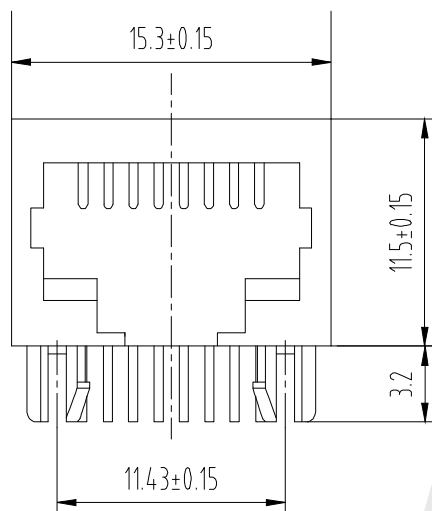


HSF



RoHS



PC Board Layout
Component Side Shown

NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE $t=0.3\text{mm}$
3. PLATING: SELECTING GOLD PLATING $1\mu\sim 50\mu$ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATIN. OVER NICKEL IN SOLDER AREA
4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE

ELECTRICAL

1. VOLTAGE RATING: 125VAC RMS
2. CURRENT RATING: 1.5AMP
3. CONTACT RESISTANCE: 30MILLIOHMS MAX
4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTTON PRB-SOLDER: 1 LB MIN

REVRONMENTAL

1. STORAGE: -40°C TO 85°C
2. OPERATION: 0°C TO 70°C

Order code:

ATRJ5623 - 10P - 8C - X - A - A

①	②	③	④	⑤	⑥
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① SERIES NO:

② NUMBER OF POSITIONS (10P, 8P, 6P, 4P)

③ NUMBER OF CONTACTS (10C, 8C, 6C, 4C)

④ Contact Plating

G0: Gold flash

G1: 3U" Gold

G2: 5U" Gold

G3: 10U" Gold

G4: 15U" Gold

G5: 30U" Gold

SN: Tin

⑤ Shield

A: W/O Shield

B: Half Shield

C: Shield W/Eml

D: Shield W/O Eml

⑥ Ports

A: 1X1P

B: 1X2P

C: 1X4P

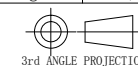
D: 1X5P

E: 1X6P

F: 1X8P

Unless Otherwise specified tolerance
X. ± 0.35 X. XX: ± 0.20
X. X: ± 0.25 X. XXX: ± 0.15

SCALE: As Shown UNIT: mm
DRAW Wu Feng Rong DATE 22/03/2018
CHECK BobYang DATE 22/03/2018



ANTENK ELECTRONICS CO., LTD

Http://www.antenk.com

E-mail: sales@antenk.com

TITLE: RJ45 Jack side entry, Full
Plastic with bump

DRAWING NO: ATRJ5623-10P8C-X-A-A

PRODUCT NO: ATRJ5623-10P8C-X-A-A

REV

DESCRIPTION

DATE

1

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4

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